



Material Content Data Sheet



Sales Product Name		BSZ900N15NS3 G		Issued		20. July 2018		
MA#		MA001326358						
Package		PG-TSDSON-8-2		Weight*		38.25 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.118	2.92	2.92	29239	29239
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		55	
	non noble metal	zinc	7440-66-6	0.008	0.02		219	
	non noble metal	iron	7439-89-6	0.168	0.44		4383	
wire	non noble metal	copper	7440-50-8	6.808	17.80	18.27	177988	182645
	non noble metal	copper	7440-50-8	0.027	0.07	0.07	699	699
	encapsulation	organic material	carbon black	1333-86-4	0.035	0.09		917
encapsulation	plastics	epoxy resin	-	1.807	4.72		47239	
	inorganic material	silicondioxide	60676-86-0	15.700	41.06	45.87	410473	458629
	leadfinish	non noble metal	tin	7440-31-5	0.387	1.01	1.01	10122
plating	noble metal	silver	7440-22-4	0.963	2.52	2.52	25167	25167
solder	noble metal	silver	7440-22-4	0.034	0.09		879	
	non noble metal	tin	7440-31-5	0.027	0.07		704	
	non noble metal	lead	7439-92-1	1.285	3.36	3.52	33596	35179
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		28	
	non noble metal	zinc	7440-66-6	0.004	0.01		113	
	non noble metal	iron	7439-89-6	0.086	0.23		2254	
	non noble metal	copper	7440-50-8	3.501	9.15	9.39	91538	93933
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.002	0.00		49	
	non noble metal	zinc	7440-66-6	0.008	0.02		197	
	non noble metal	iron	7439-89-6	0.151	0.39		3945	
	non noble metal	copper	7440-50-8	6.127	16.02	16.43	160196	164387
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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